

Exothermic Reactions in Al/Pt Multilayers of Varied Stoichiometry

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Abstract

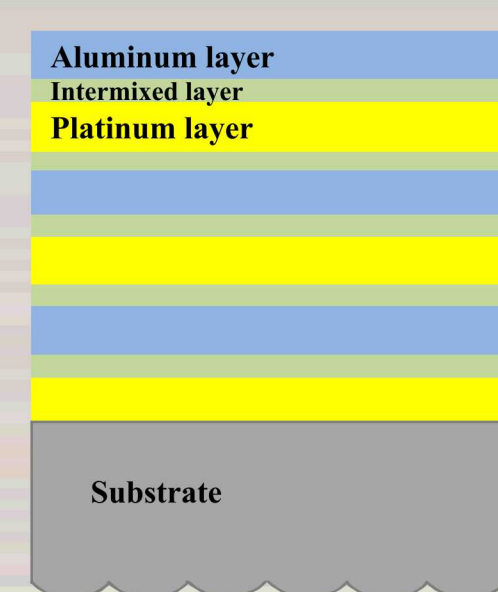
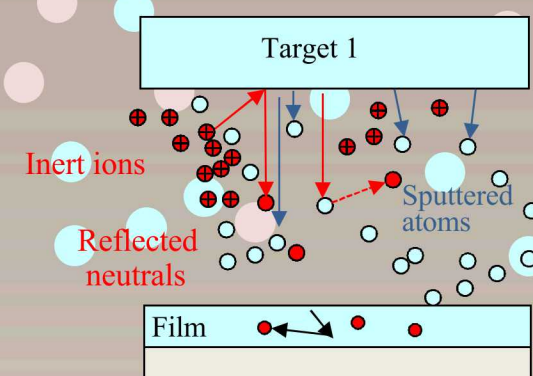
Reactive bimetallic multilayers of aluminum and platinum form an energetic material that can be ignited at a single point and undergo rapid, exothermic, self-propagating formation reactions. Reactivity has been evaluated across a broad range of stoichiometry (nAl:mPt) and layer periodicity. Experiments demonstrate self-propagating reactions in ~1.6 micron-thick Al/Pt multilayers when the molar ratio of reactants is in the range 4Al:1Pt to 1Al:4Pt. This rather large compositional range is characterized by different reaction rates and behaviors. High-speed photography shows that equimolar Al/Pt multilayers undergo the most rapid reactions with wavefront speeds as large as 80 m/s. Al- and Pt-rich multilayers react at reduced rates with speeds as low as 1 m/s. Ongoing work will explore how this broad range of composition can be used to benefit joining and other related applications.

Process Parameters and Initial Deposited Structure

Sputter Growth of Reactive Films¹⁻³

Sputtering Process used for Al/Pt Multilayers

- Chamber base pressure: 10^{-7} Torr
- Throttled chamber pressure: 10 mTorr
- Each material was sputtered at rates in the range from 200-400 Å/min.
- No deliberate heating. Estimated deposition temperature ~50°C.

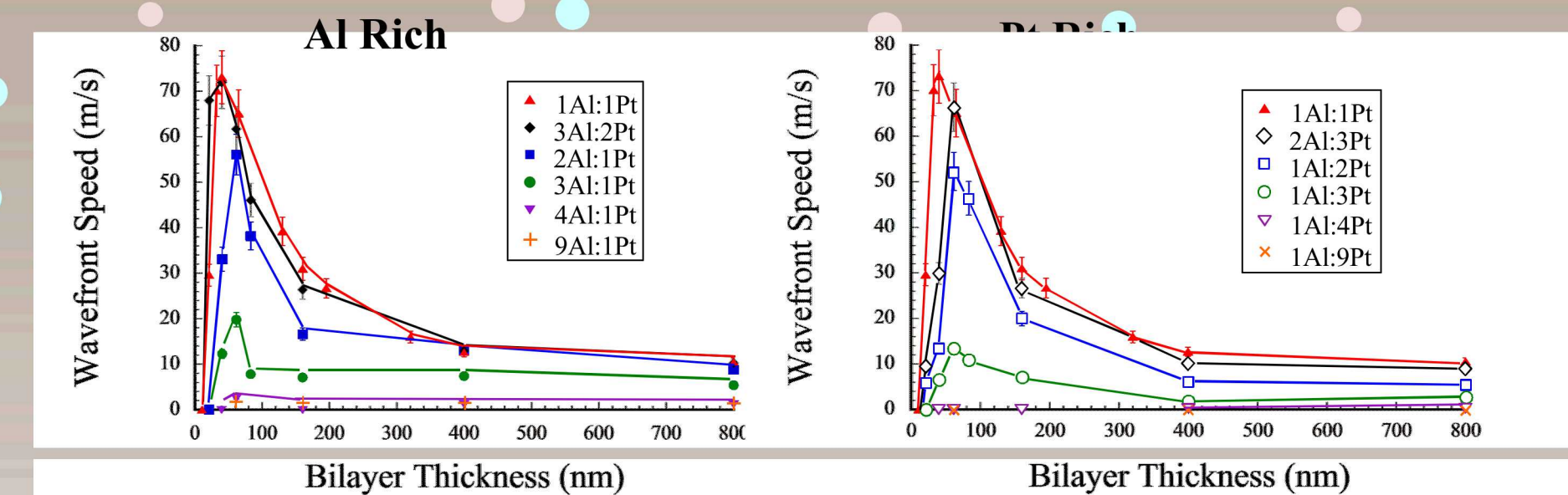


Characteristics of Aluminum - Platinum Multilayers

- Aluminum and platinum are grown in alternating thin film layers.
- The reactive layers undergo intermixing at the Al/Pt interface during film growth.
- The intermixed layer has been shown in prior work to have an effect on stored chemical energy and propagating reactions.

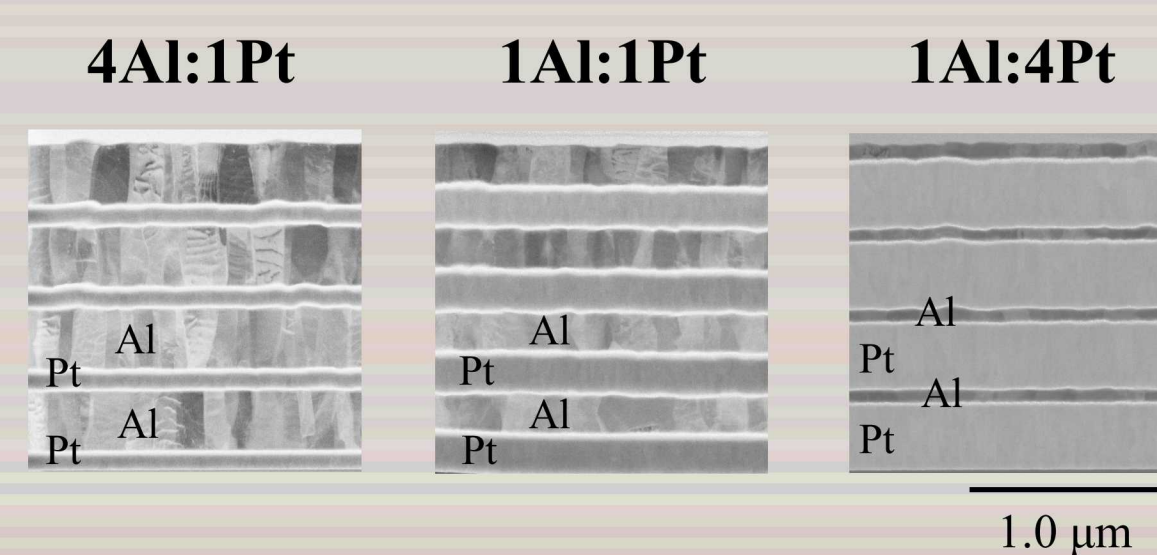
Reaction Speed as a Function of Composition and Bilayer Thickness

Composition and Reaction Speed



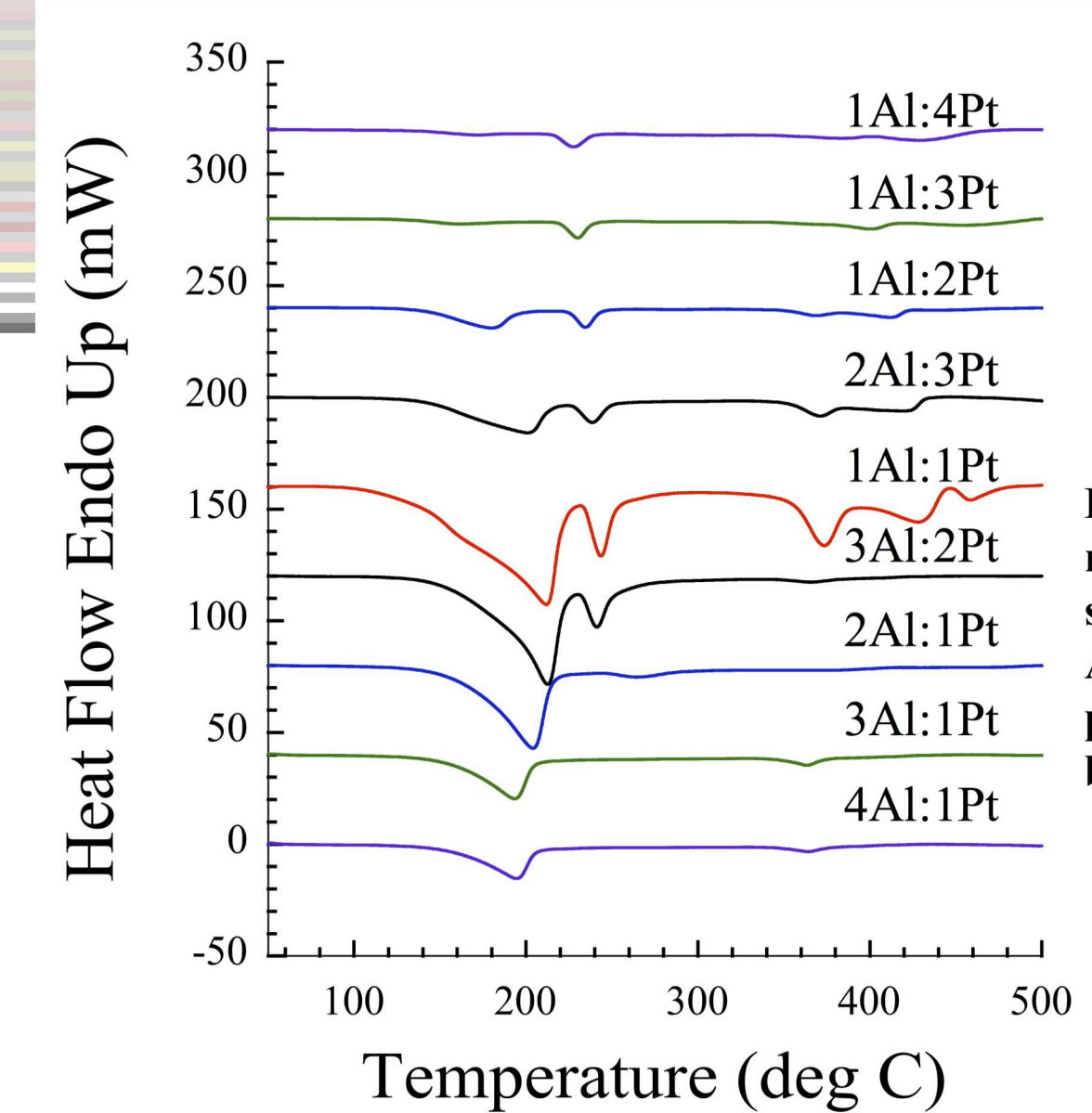
Observations prior to Reaction

STEM of Al/Pt Films (3 compositions)



Differential Scanning Calorimetry of Various Al:Pt Stoichiometry

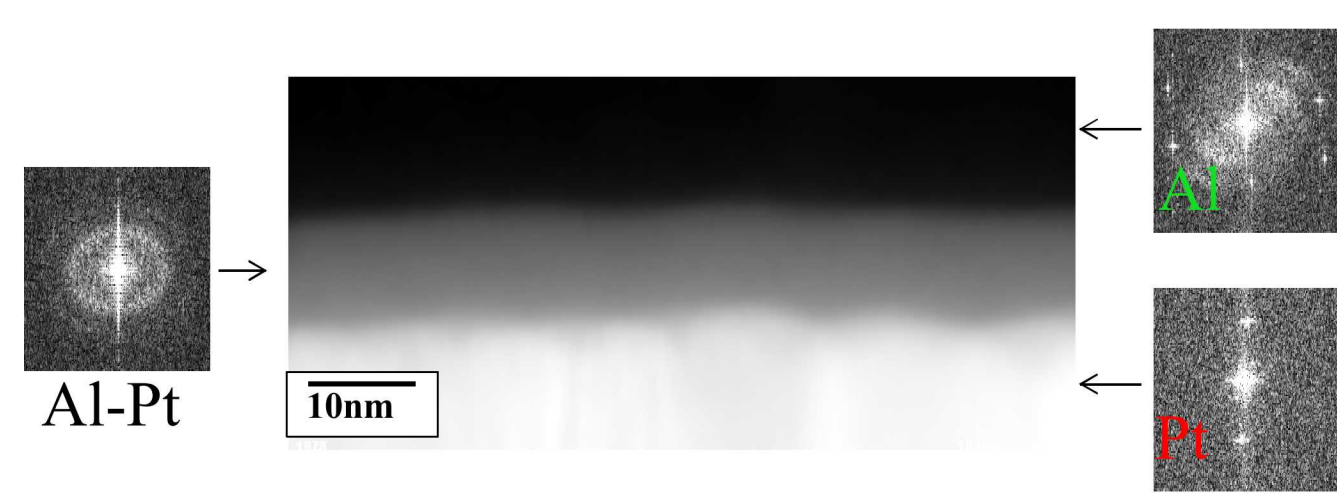
Samples are measured by differential scanning calorimetry (DSC). The samples are taken through a heating profile which allows us to observe the heat profile and compare it to known standards and to observe the effects of various compositions.



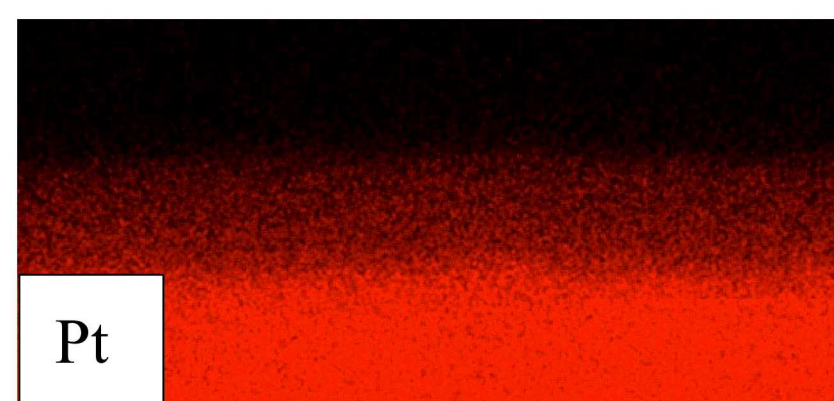
DSC thermograms for Al-Pt multilayers of different stoichiometry are included. All samples described in this plot were made with a bilayer thickness of 61.5 nm.

Pt/Al Bilayer Analyzed by TEM and EDS

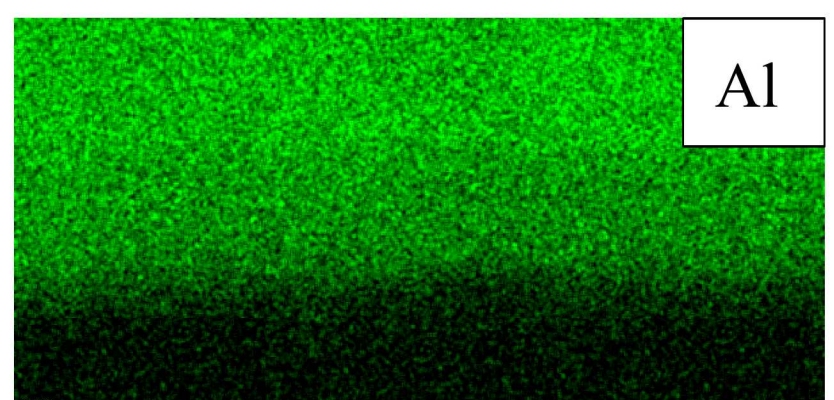
TEM Cross Section of Pt/Al Bilayer Shows Intermixed Volumes



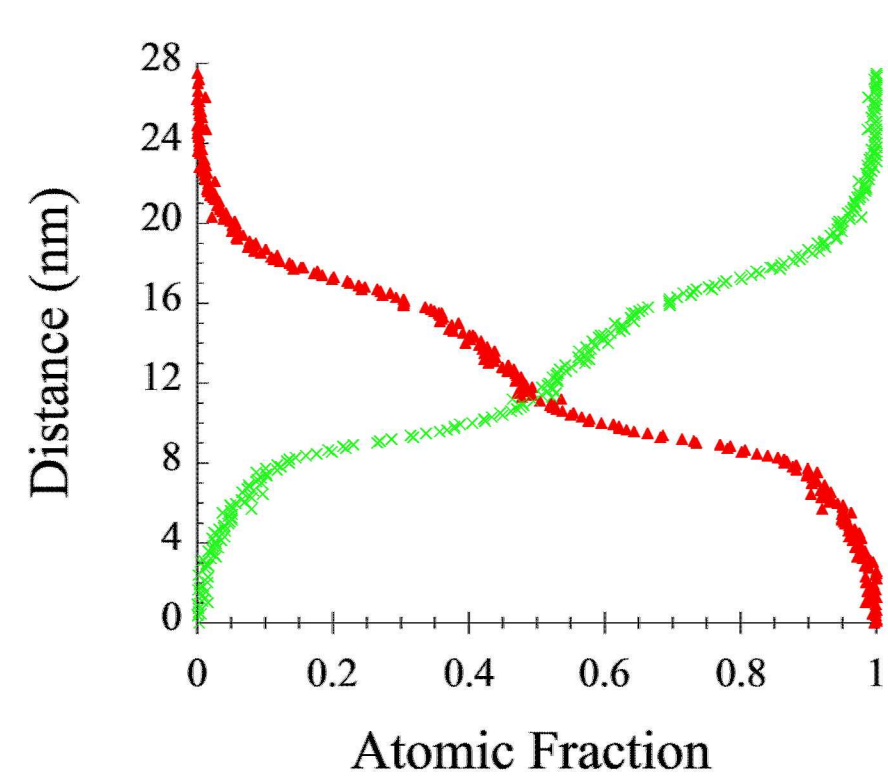
EDS Analysis of Bilayer Cross-Section, Pt in Red



EDS Analysis of Bilayer Cross-Section, Al in Green

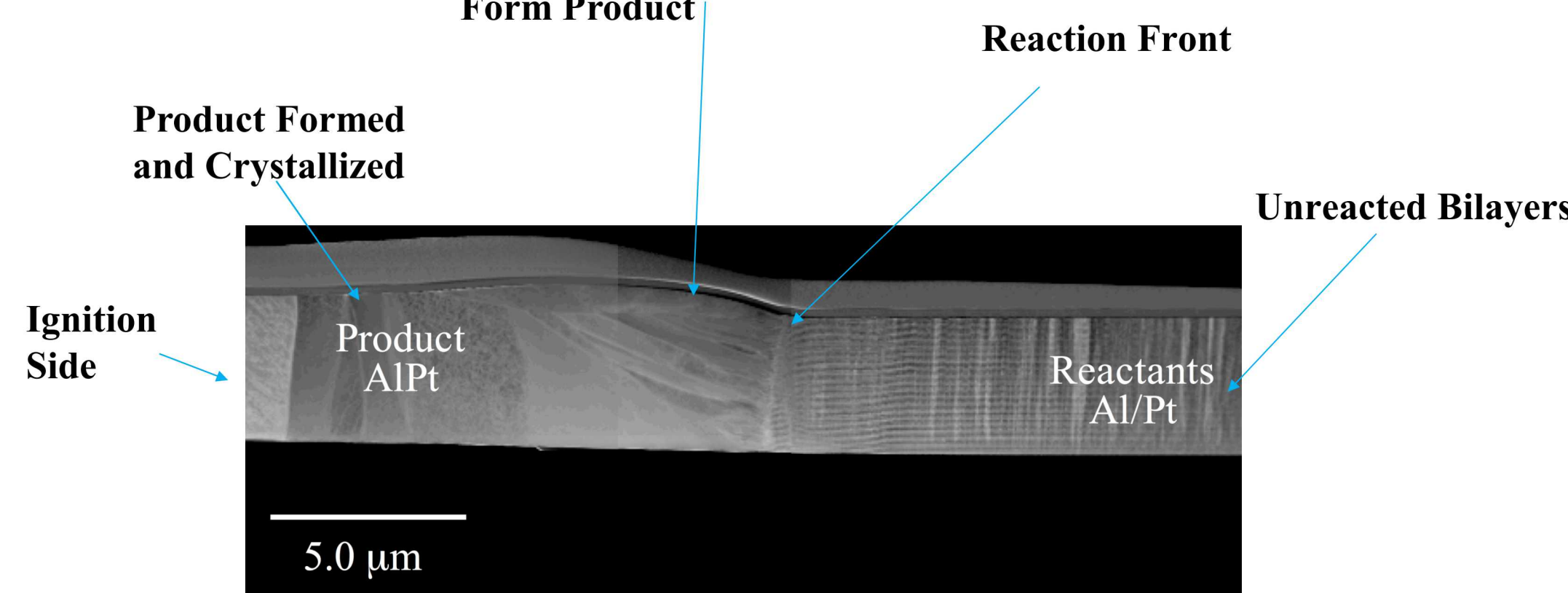


Plot of Atomic Fraction of Al/Pt based on EDS Results



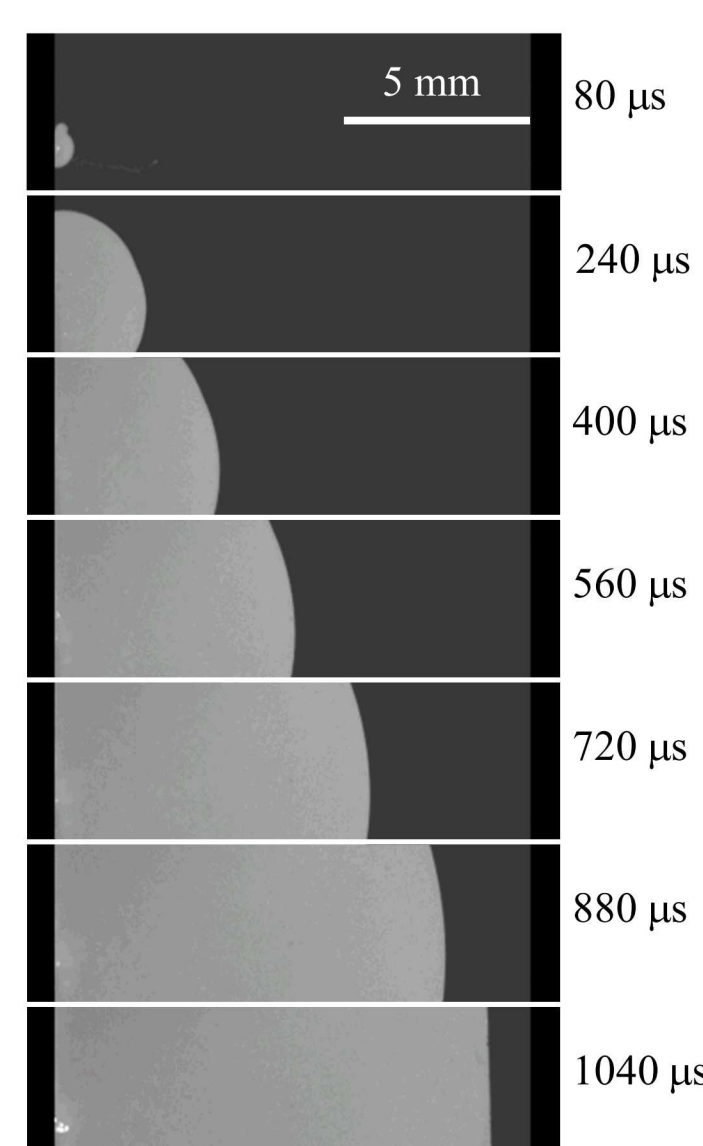
Quenched Wavefront for Demonstrating Changes that Occur during Self-Propagating Reactions

Ignition has Occurred, Product is Forming, Heat being Given Off as Reactants Combine to Form Product



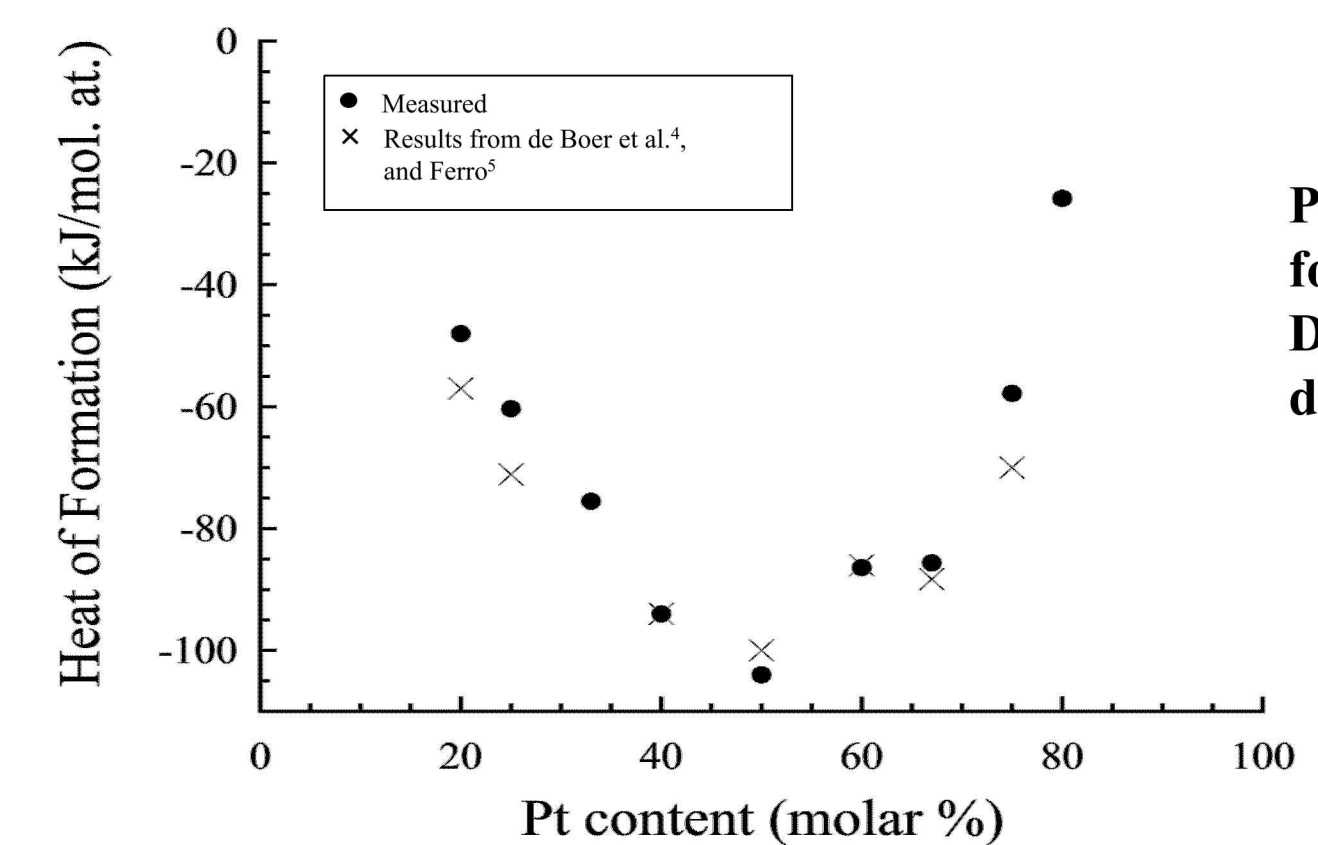
- This image was obtained after partial reaction.
- Multilayer was ignited in a region that was detached from substrate. When the reaction front reached the silicon, the substrate acted as a heat sink and stopped the reaction.
- The Al/Pt undergoes a volumetric expansion as a result of the formation reaction as seen to the left of the reaction front.
- Unreacted material is visible to the right of the reaction front in this image.

Images of Reaction Captured by Plan View High-Speed Photography



- Steady propagation is characterized by a uniform, single velocity (per multilayer).
- There is no evidence of instabilities.

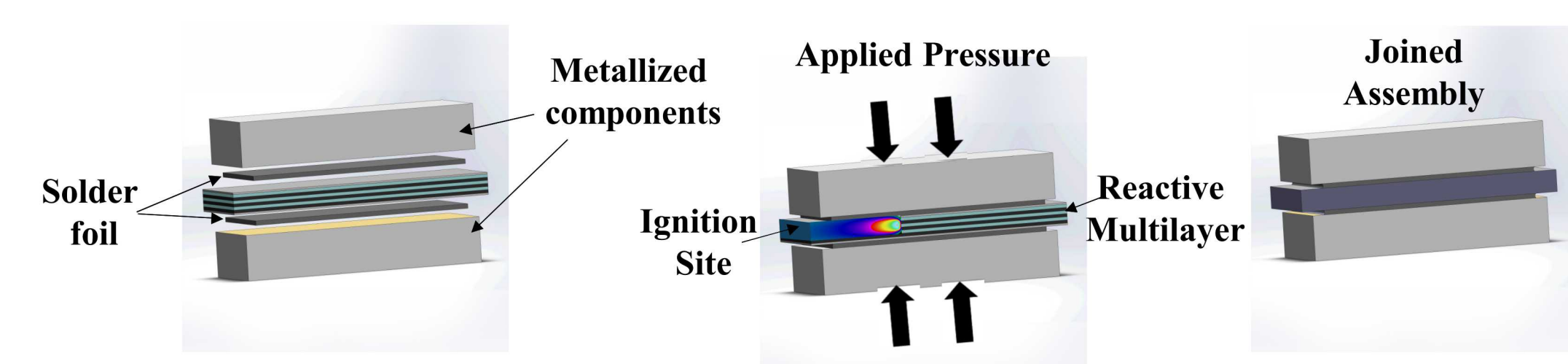
Heat of Formation



Plot of heat of formation derived from DSC thermograms and data from literature

Future Work: Joining with Thin Multilayers

J. Brauer⁶ demonstrated successful joining using a micron-thin Al/Pd multilayer and a Sn solder layer.



References

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